2SD1485

Silicon PNP triple diffusion planar type

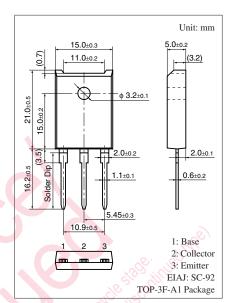
For high power amplification Complementary to 2SB1054

■ Features

- \bullet Excellent collector current I_C characteristics of forward current transfer ratio h_{FE}
- Wide safe operation area
- High transition frequency f_T
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	100	V
Collector-emitter voltage (Base open)	V _{CEO}	100	V
Emitter-base voltage (Collector open)	V _{EBO}	5	V
Collector current	$I_{\rm C}$	5	A
Peak collector current	I_{CP}	8	A
Collector power dissipation	P _C	60	W
$T_a = 25^{\circ}C$		3.0	
Junction temperature	T_{j}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



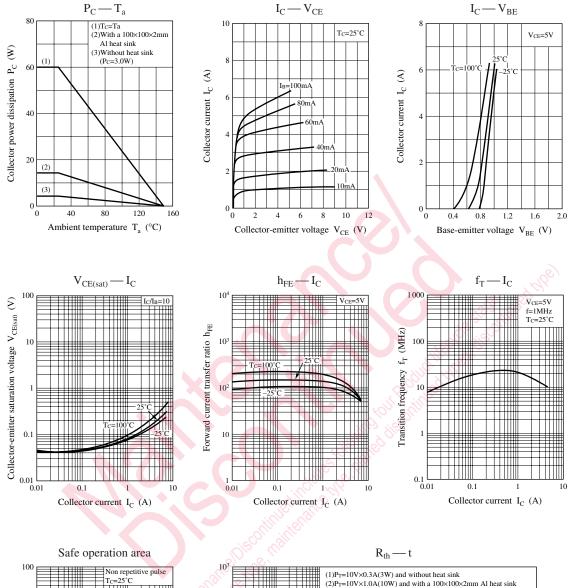
■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

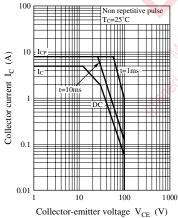
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Base-emitter voltage	V _{BE}	$V_{CE} = 5 \text{ V}, I_{C} = 3 \text{ A}$			1.8	V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 100 \text{ V}, I_{E} = 0$			50	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 3 \text{ V}, I_{C} = 0$			50	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 5 \text{ V}, I_{C} = 20 \text{ mA}$	20			_
	h _{FE2} *	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	60		200	
60	h _{FE3}	$V_{CE} = 5 \text{ V}, I_{C} = 3 \text{ A}$	20			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 3 \text{ A}, I_B = 0.3 \text{ A}$			2.0	V
Transition frequency	f_T	$V_{CE} = 5 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		90		pF
(Common base, input open circuited)						

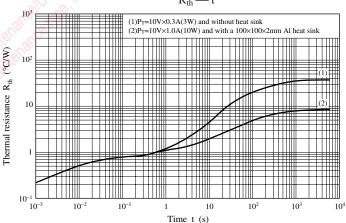
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	Р
h _{FE2}	60 to 120	100 to 200







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